

10 9 8 7 6 5 4 3 2 1

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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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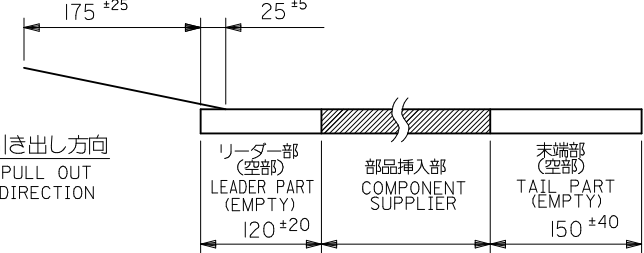
4

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注記  
NOTES

- 53261-\*\*-19 の詳細寸法については図面 SD-53261-024 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART  
トップテープ未接着部 TOP TAPE NON-BONDED PART



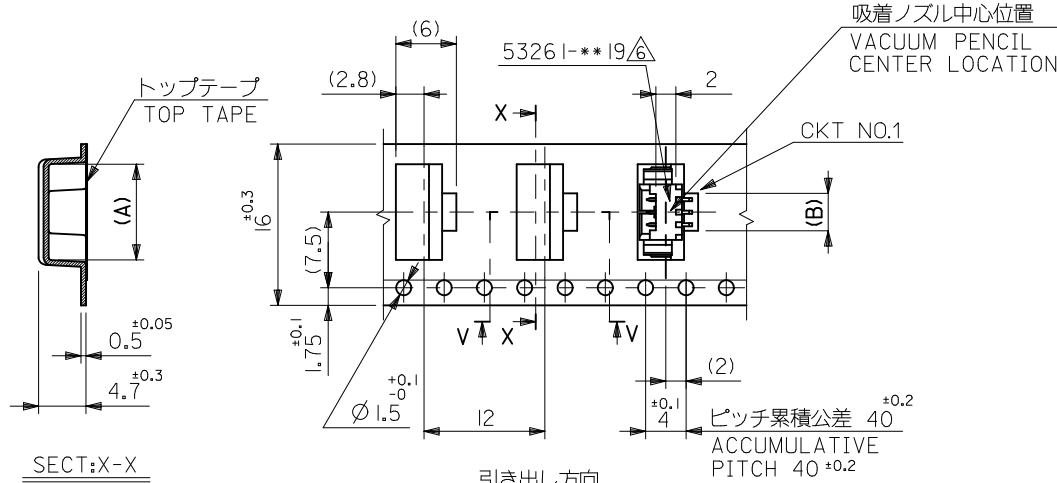
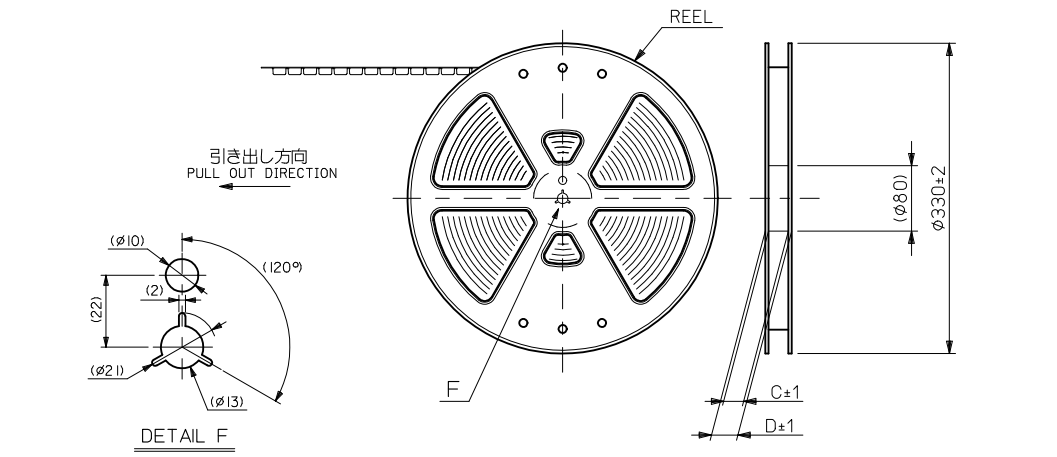
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

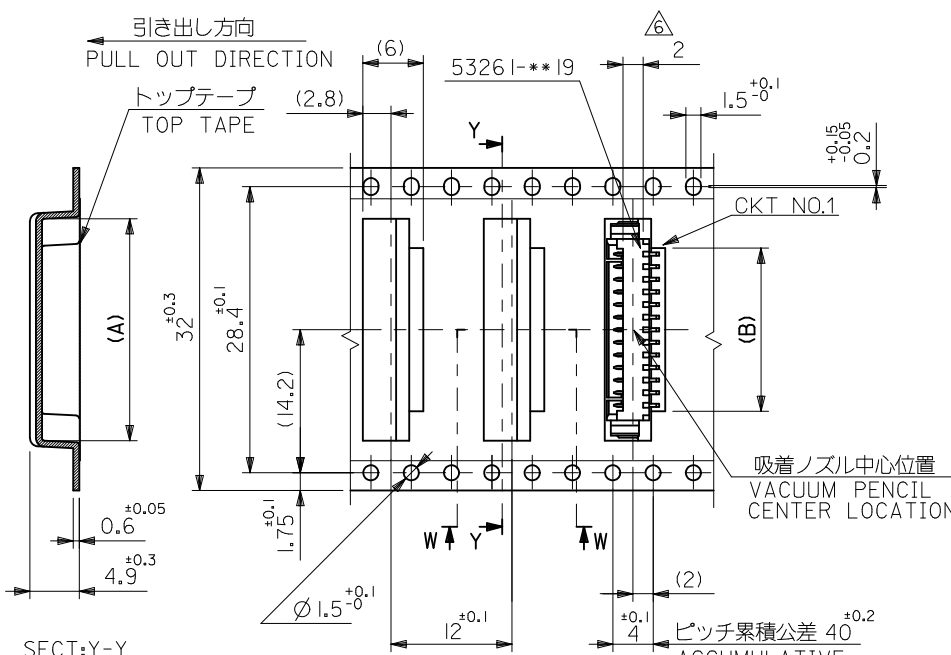
△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-\*\*-90 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-90
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

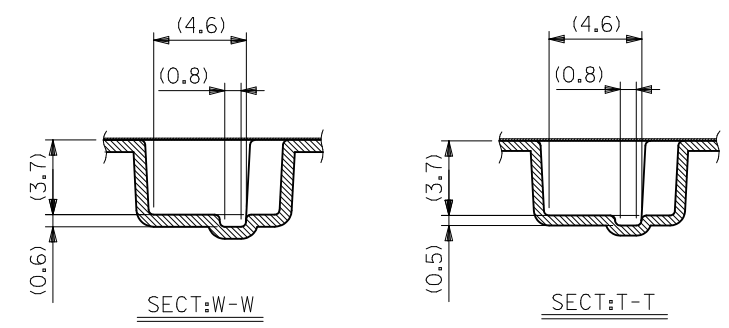
16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED EC NO: D	DESCRIPTION 2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/06	APPROVED BY NUKITA 2010/02/18				
		30 OVER	±0.3	MATERIAL NO. SEE TABLE & SHEET 2,3		DOCUMENT NO. SD-53261-023		SHEET NO. 1 OF 3		
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

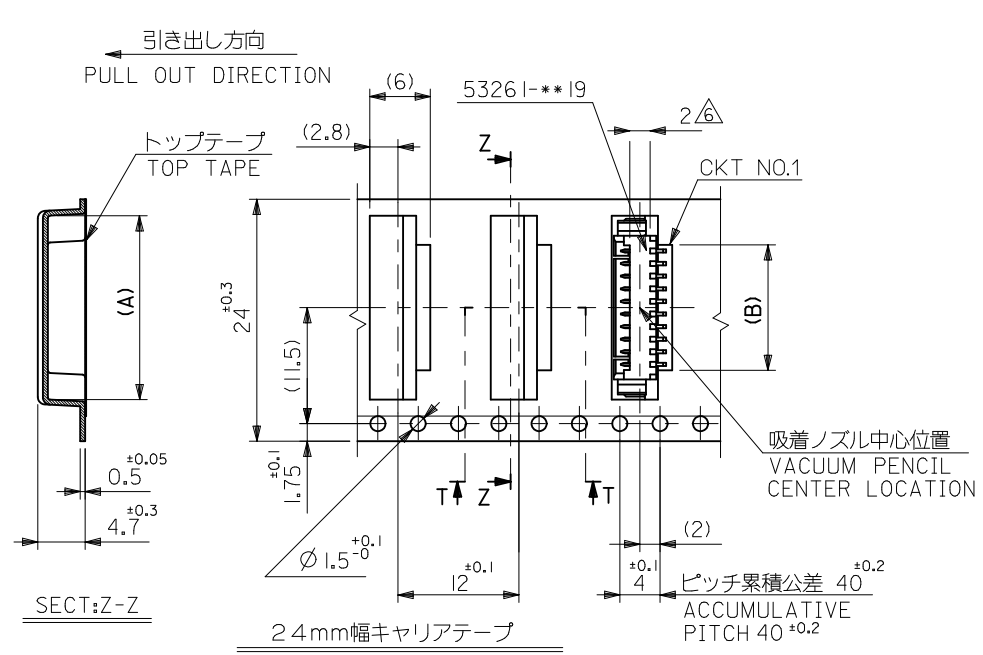




SECT:Y-Y  
32mm幅キャリアテープ  
32mm WIDTH CARRIER TAPE



SECT:W-W  
SECT:T-T

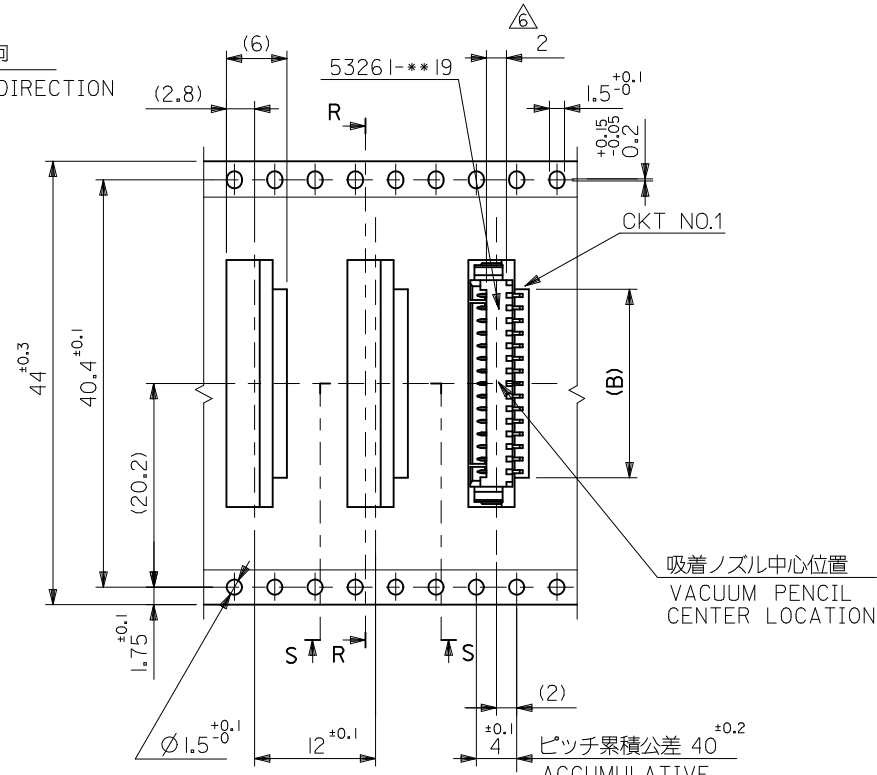
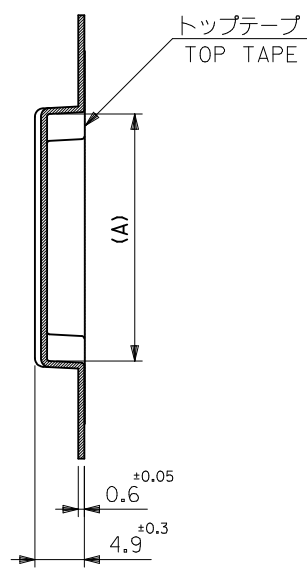


SECT:Z-Z  
24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

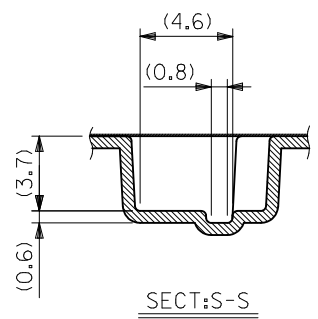
32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
4.95	10.75	53261-0471	4			

MODEL NO.	53261-***71	キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY			SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
EC NO.	DRWN:YGOITO CHKD:KASAKAWA APPR:	10 UNDER ±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			SHEET NO. 2 OF 3
REV		10 OVER 30 UNDER ±0.25	CHECKED BY K. TOJO	DATE '04/02/06	MOLEX INCORPORATED			
		30 OVER ±0.3	APPROVED BY NUKITA	DATE 2010/02/18	DOCUMENT NO. SD-53261-023			
		ANGULAR ±3 °	MATERIAL NO. SEE TABLE & SHEET 1.3					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

引き出し方向  
PULL OUT DIRECTION

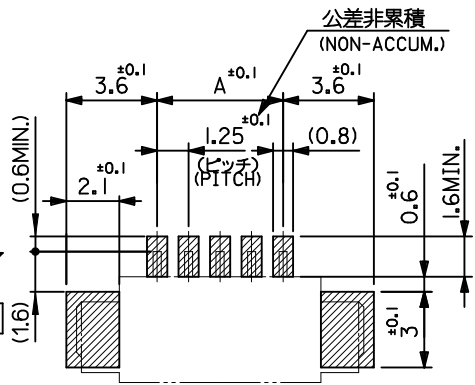
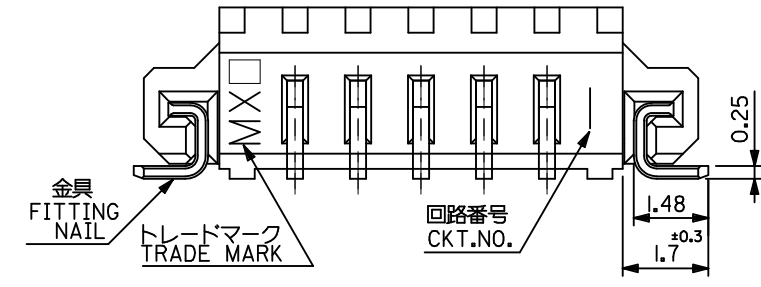
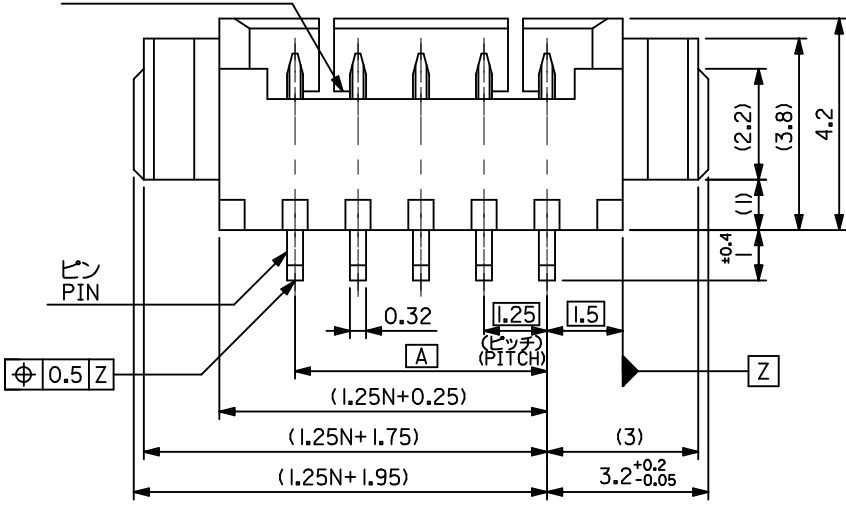
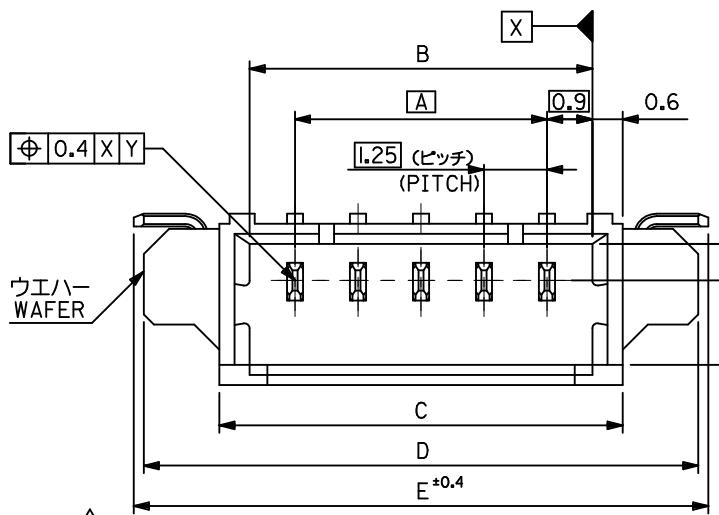


44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

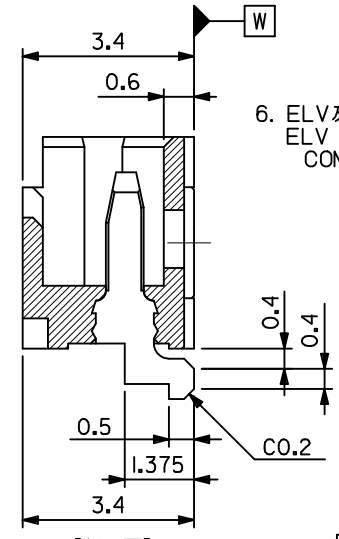


44	49.4	45.4	18.7	24.5	53261-1571	15
			17.45	23.25	53261-1471	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17	10 UNDER ±0.2	MM ONLY	---	METRIC	☉ □
DRWN: YGOTO		10 OVER 30 UNDER ±0.25	DRAWN BY DATE	TITLE		
CHKD: KASAKAWA		30 OVER ±0.3	H. SHIMABUKUR '04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
APPR:		ANGULAR ±3 °	CHECKED BY DATE	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	K. TOJO '04/02/06	DOCUMENT NO. SD-53261-023		
			APPROVED BY DATE	SHEET NO. 3 OF 3		
			NUKITA 2010/02/18	SEE TABLE & SHEET 12		
			MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SIZE A3			



参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)  
(SCALE 5:1)



【断面図】  
[CROSS SECTION]

注記 NOTES

1. 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
PIN: PHOS-BRO  
銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
金具: リン青銅  
FITTING NAIL: PHOS-BRO  
銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
3. ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。  
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.
5. 本製品は 53261-\*\*10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*10

26.4	26	23	21.8	20	53261-1719	17
23.9	23.5	20.5	19.3	17.5	-1519	15
22.65	22.25	19.25	18.05	16.25	-1419	14
21.4	21	18	16.8	15	-1319	13
20.15	19.75	16.75	15.55	13.75	-1219	12
18.9	18.5	15.5	14.3	12.5	-1119	11
17.65	17.25	14.25	13.05	11.25	-1019	10
16.4	16	13	11.8	10	-0919	9
15.15	14.75	11.75	10.55	8.75	-0819	8
13.9	13.5	10.5	9.3	7.5	-0719	7
12.65	12.25	9.25	8.05	6.25	-0619	6
11.4	11	8	6.8	5	-0519	5
10.15	9.75	6.75	5.55	3.75	-0419	4
8.9	8.5	5.5	4.3	2.5	-0319	3

53261-**19	7.65	7.25	4.25	3.05	1.25	53261-0219	2
MODEL NO.	E	D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2012-1315 2012/04/16 DRWN: ITO CHKD: KASAKAWA 2012/04/16 APPR: Y01TO 2012/04/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06			
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06			
ANGULAR	±3 °	MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-024		SHEET NO. 1 OF 1	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					